

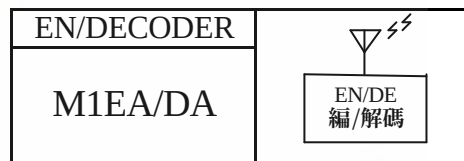


一華半導體股份有限公司
MOSDESIGN SEMICONDUCTOR CORP.

TAIPEI : TEL : 886-2- 22783733
FAX : 886-2- 22783633
H.K. TEL : 852- 27569109
FAX : 852- 27566961

SAME Rosc in EN/DE
S.O.DIP

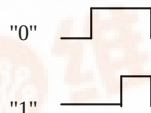
使用同一電阻



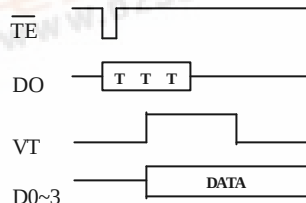
FEATURES 功能敘述

- Momentary DATA — suffix-M.
- S.O.Package 18P — suffix-S.
- Direct Data Transmit — suffix-H : switch to VDD.

BIT FORMAT



PROTOCOL



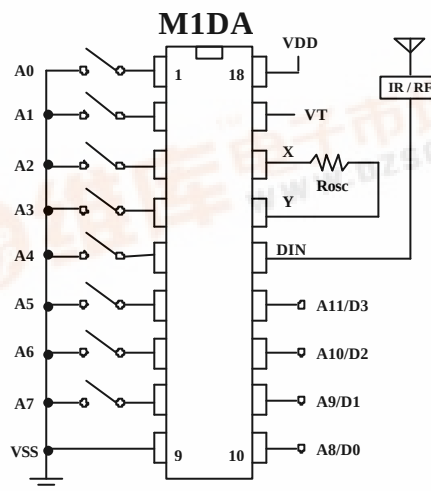
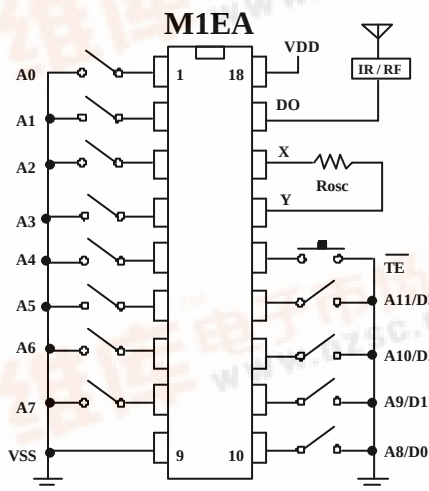
APPLICATION 產品應用

- Security alarm, Remote control. 防盜系統, 任何遙控裝置.

ELECTRICAL CHARACTERISTICS 電氣規格

Characteristics	Sym.	Min.	Typ.	Max.	Unit	REMARKS
工作電壓 Operating Voltage	V_{DD}	2.4	—	13	V	
工作電流 Operating Current	I_{OP}	—	0.1	1	mA	No load
靜態電流 Quiescent Current	I_{SB}	—	1	10	uA	
推動電流 Driving Current	I_{OL}	—	2	—	mA	@ $V_{DS}=1.2V$
振盪頻率 Oscillator Frequency	F_{OSC}	—	76	—	KHz	External $\pm 30\%$
工作溫度 Operating Temperature	Temp.	-20	25	60	$^{\circ}C$	

APPLICATION DIAGRAM 參考電路圖



Rosc-M1EA: 270 K Ω , M1DA : 270 K Ω

All specs and applications shown above subject to change without prior notice.

(以上電路及規格僅供參考,本公司得逕行修正)

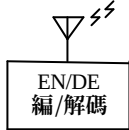


一華半導體股份有限公司
MOSDESIGN SEMICONDUCTOR CORP.

TAIPEI : TEL : 886-2- 22783733
FAX : 886-2- 22783633
H.K. TEL : 852- 27569109
FAX : 852- 27566961

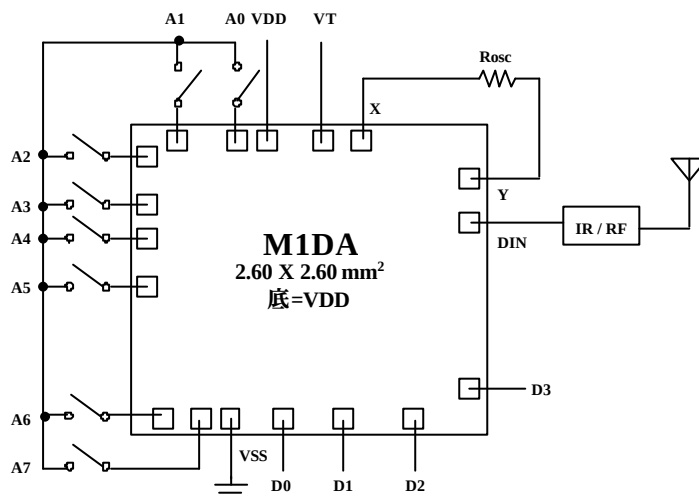
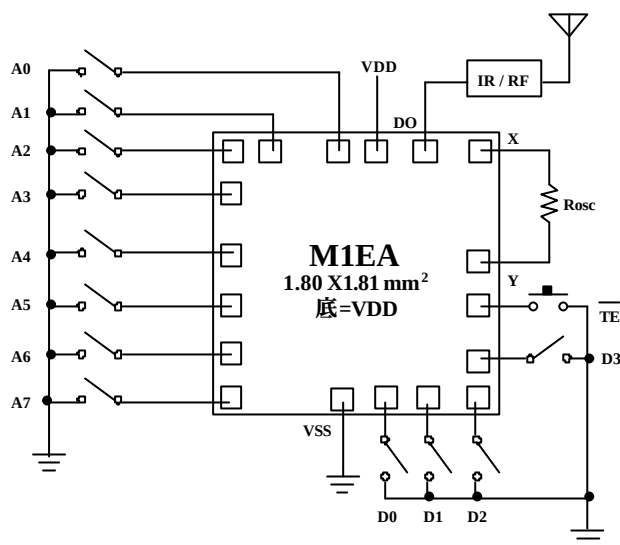
SAME Rosc in EN/DE
S.O.DIP

使用同一電阻

EN/DECODER	
M1EA/DA	

APPLICATION DIAGRAM 參考電路圖

CHIP FORM



* Rosc~M1EA : 270 K Ω , M1DA : 270 K Ω

* All specs and applications shown above subject to change without prior notice.

(以上電路及規格僅供參考,本公司得逕行修正)



一華半導體股份有限公司
MOSDESIGN SEMICONDUCTOR CORP.

TAIPEI : TEL : 886-2- 22783733
FAX : 886-2- 22783633
H.K. TEL : 852- 27569109
FAX : 852- 27566961

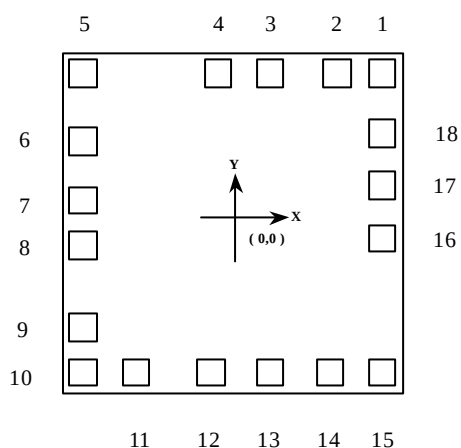
SAME R_{osc} in EN/DE
S.O.DIP

使用同一電阻

EN/DECODER	
M1EA/DA	EN/DE 編/解碼

PAD ASSIGNMENT & POSITION

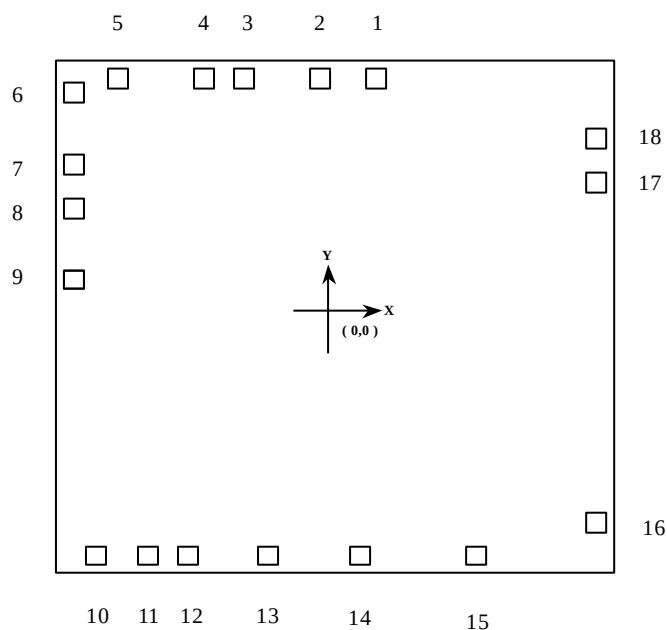
M1EA :



UNIT : μm

No.	NAME	X	Y
1	A10 / D2	728	732.5
2	A11 / D3	528	732.5
3	TEB	211	732.5
4	Y	-31.5	732.5
5	X	-728.5	732.5
6	DOUT	-728.5	376.5
7	VDD	-728.5	36
8	A0	-728.5	-164
9	A1	-728.5	-533
10	A2	-728.5	-733
11	A3	-480.5	-733
12	A4	-101	-733
13	A5	184	-733
14	A6	480	-733
15	A7	728	-733
16	VSS	728	-66
17	A8 / D0	728	183
18	A9 / D1	728	431.5

M1DA :



UNIT : μm

No.	NAME	X	Y
1	X	259.5	1096.5
2	VT	-9.5	1096.5
3	VDD	-347	1096.5
4	A0	-547	1096.5
5	A1	-950	1096.5
6	A2	-1150	1025
7	A3	-1150	702
8	A4	-1150	502
9	A5	-1150	179
10	A6	-1043	-1100
11	A7	-799.5	-1100
12	VSS	-599.5	-1100
13	A8 / D0	-251	-1100
14	A9 / D1	169	-1100
15	A10 / D2	696	-1100
16	A11 / D3	1145.5	-946
17	DIN	1086	590
18	Y	1086	790

* M1EA CHIP SIZE $\sim 1.80 \times 1.81 \text{ mm}^2$

* M1DA CHIP SIZE $\sim 2.60 \times 2.60 \text{ mm}^2$

* IC substrate should be connected to VDD in PCB (PCB 上 IC 必須接 VDD)